

4MBI300VG-120R-50

IGBT Modules

IGBT MODULE (V series)

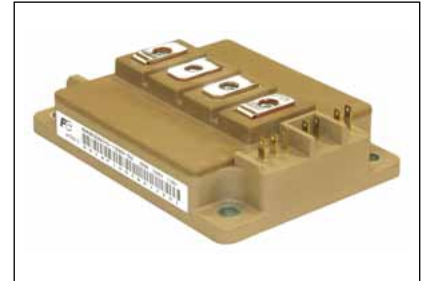
1200V / 300A / IGBT, 600V/300A/RB-IGBT, 4 in one package

■ Features

- Higher Efficiency
- Optimized A (T-type) -3 level circuit
- Low inductance module structure
- Featuring Reverse Blocking IGBT (RB-IGBT)

■ Applications

- Inverter for Motor Drive
- Uninterruptible Power Supply
- Power conditioner



■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings (at T_c=25°C unless otherwise specified)

Items		Symbols	Conditions		Maximum ratings	Units	
T1, T2	Collector-Emitter voltage	V _{CEs}			1200	V	
	Gate-Emitter voltage	V _{GEs}			±20	V	
	Collector current	IGBT	I _c	Continuous	T _c =80°C	300	A
			I _{cp}	1ms	T _c =80°C	600	
		FWD	-I _c			300	
			-I _{c pulse}	1ms		600	
Collector power dissipation	P _c	1 device		1250	W		
T3, T4	Collector-Emitter voltage	V _{CEs}			600	V	
	Gate-Emitter voltage	V _{GEs}			±20	V	
	Collector current	I _c	Continuous	T _c =80°C	300	A	
		I _{cp}	1ms	T _c =80°C	600		
Collector power dissipation	P _c	1 device		1250	W		
Junction temperature		T _j			150	°C	
Case temperature		T _c			125		
Storage temperature		T _{stg}			-40 ~ +125		
Isolation voltage	between terminal and copper base (*1)	V _{iso}	AC : 1min.		2500	VAC	
Screw torque	Mounting (*2)	-	M5 or M6		3.5	N m	
	Terminals (*3)	-	M5		3.5		

Note *1: All terminals should be connected together during the test.

Note *2: Recommendable value : 2.5-3.5 Nm (M5 or M6)

Note *3: Recommendable value : 2.5-3.5 Nm (M5)

● Electrical characteristics (at $T_j = 25^\circ\text{C}$ unless otherwise specified)

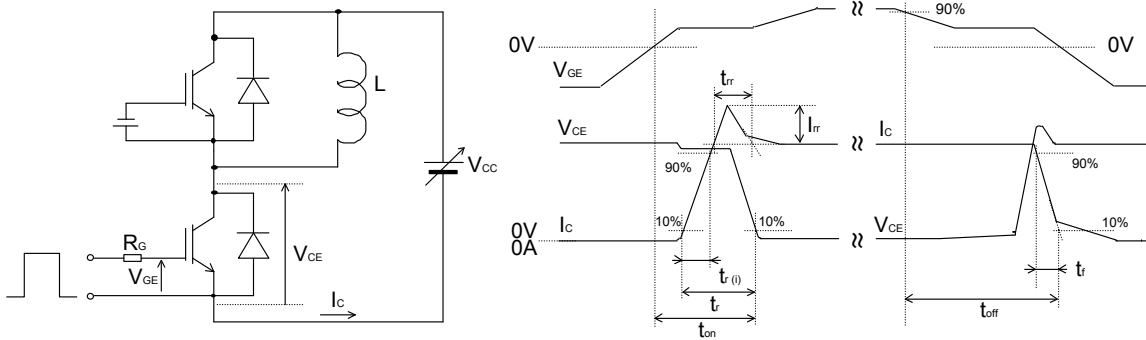
Items	Symbols	Conditions	Characteristics			Units		
			min.	typ.	max.			
T1, T2	Zero gate voltage collector current	I_{CES}	$V_{GE} = 0V, V_{CE} = 1200V$	-	-	2.0	mA	
	Gate-Emitter leakage current	I_{GES}	$V_{CE} = 0V, V_{GE} = \pm 20V$	-	-	400	nA	
	Gate-Emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = 20V, I_c = 300mA$	6.0	6.5	7.0	V	
	Collector-Emitter saturation voltage	$V_{CE(sat)}$ (chip)	$V_{GE} = 15V$ $I_c = 300A$	$T_j = 25^\circ\text{C}$	-	1.85	2.10	V
				$T_j = 125^\circ\text{C}$	-	2.20	-	
		$V_{CE(sat)}$ (terminal)	$V_{GE} = 15V$ $I_c = 300A$	$T_j = 25^\circ\text{C}$	-	2.05	2.35	
				$T_j = 125^\circ\text{C}$	-	2.40	-	
	Input capacitance	C_{ies}	$V_{CE} = 10V, V_{GE} = 0V, f = 1MHz$	-	25.2	-	nF	
	Turn-on time	t_{on}	SW mode : A $V_{CC} = 800V$ $I_c = 300A$ $V_{GE} = \pm 15V$		-	1.10	1.90	μs
		t_r			-	0.70	1.25	
		$t_{r(f)}$			-	0.14	-	
	Turn-off time	t_{off}	$R_G = +10/-1\Omega$		-	0.62	1.10	μs
t_f				-	0.09	0.35		
Forward on voltage	V_F (chip)	$I_F = 300A$	$T_j = 25^\circ\text{C}$	-	1.70	1.95	V	
			$T_j = 125^\circ\text{C}$	-	1.85	-		
	V_F (terminal)	$I_F = 300A$	$T_j = 25^\circ\text{C}$	-	1.95	2.25		
			$T_j = 125^\circ\text{C}$	-	2.10	-		
Reverse recovery time	t_{rr}	SW mode : A $V_{CC} = 800V$ $V_{GE} = \pm 15V$ $I_F = 300A$ $R_G = +10/-1\Omega$		-	-	0.35	μs	
T3, T4	Zero gate voltage collector current	I_{CES}	$V_{GE} = 0V, V_{CE} = 600V$	-	-	3.0	mA	
	Gate-Emitter leakage current	I_{GES}	$V_{CE} = 0V, V_{GE} = \pm 20V$	-	-	600	nA	
	Gate-Emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = 20V, I_c = 300mA$	5.5	6.5	7.5	V	
	Collector-Emitter saturation voltage	$V_{CE(sat)}$ (chip)	$V_{GE} = 15V$ $I_c = 300A$	$T_j = 25^\circ\text{C}$	-	2.45	2.80	V
				$T_j = 125^\circ\text{C}$	-	2.60	-	
		$V_{CE(sat)}$ (terminal)	$V_{GE} = 15V$ $I_c = 300A$	$T_j = 25^\circ\text{C}$	-	2.55	2.95	
				$T_j = 125^\circ\text{C}$	-	2.70	-	
	Input capacitance	C_{ies}	$V_{CE} = 10V, V_{GE} = 0V, f = 1MHz$	-	19.5	-	nF	
	Turn-on time	t_{on}	SW mode : B $V_{CC} = 400V$ $I_c = 300A$ $V_{GE} = \pm 15V$		-	0.45	1.05	μs
		t_r			-	0.27	0.53	
		$t_{r(f)}$			-	0.12	-	
	Turn-off time	t_{off}	$R_G = +8.2/-39\Omega$		-	1.32	3.00	μs
t_f				-	0.11	0.35		
Reverse recovery time	t_{rr}	SW mode : C $V_{CC} = 400V$ $V_{GE} = \pm 15V$ $I_c = 300A$ $R_G = +10/-1\Omega$		-	-	0.30	μs	
Internal inductance	L	P-N		-	40	-	nH	
		P-M		-	33	-		
		M-N		-	33	-		

● Thermal resistance characteristics

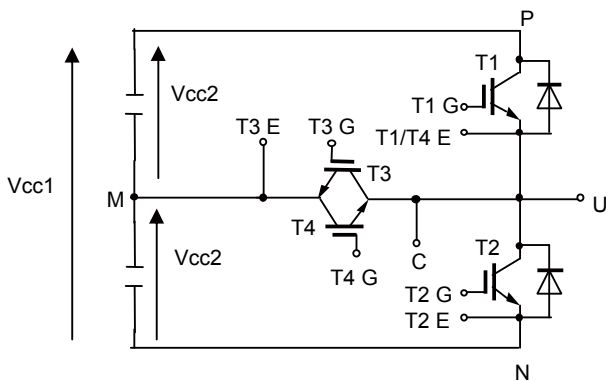
Items	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Thermal resistance (1device)	$R_{th(j-c)}$	T1, T2 IGBT	-	-	0.10	$^\circ\text{C/W}$
		T1, T2 FWD	-	-	0.16	
		T3, T4 RB-IGBT	-	-	0.10	
Contact thermal resistance (1device) (*4)	$R_{th(c-f)}$	T1, T2	-	0.025	-	
		T3, T4	-	0.017	-	

Note *4: This is the value which is defined mounting on the additional cooling fin with thermal compound (thermal conductivity = $1W/m \cdot K$).

■ Definitions of switching time



Definitions of switching mode



SW mode	Load L	T1	T2	T3	T4
A	U-N	SW	OFF	OFF	OFF
	P-U	OFF	SW	OFF	OFF
B	P-U	OFF	OFF	SW	ON
	U-N	OFF	OFF	ON	SW
C	M-U	SW	OFF	OFF	ON
	M-U	OFF	SW	ON	OFF

SW: Connect to drive circuit and input gate signal

ON: Bias voltage of gate +15V

OFF: Reverse bias voltage of gate -15V

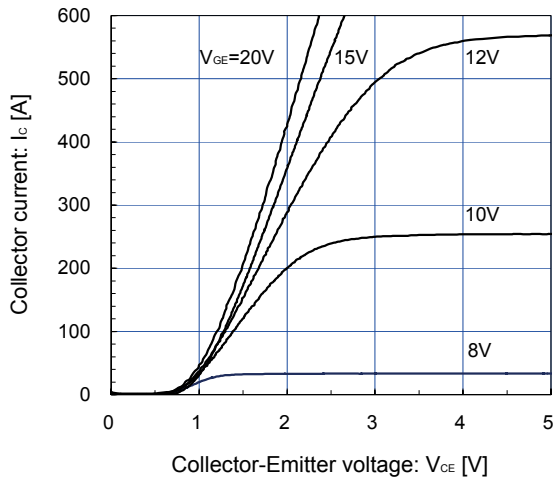
Vcc2=Vcc1/2

■ Characteristics (Representative)

[T1, T2]

Collector current vs. Collector-Emittor voltage (typ.)

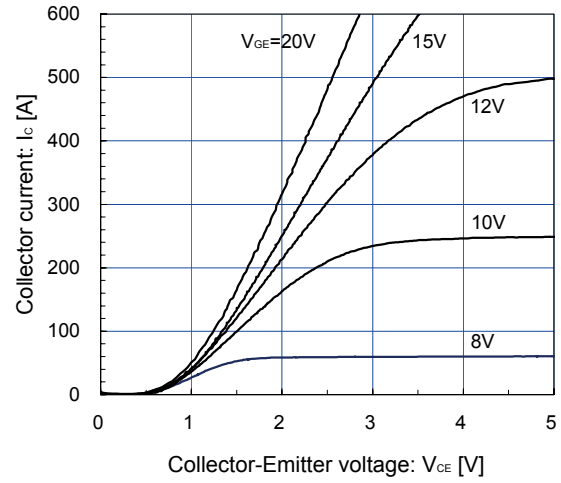
$T_j = 25^\circ\text{C}$ / chip



[T1, T2]

Collector current vs. Collector-Emittor voltage (typ.)

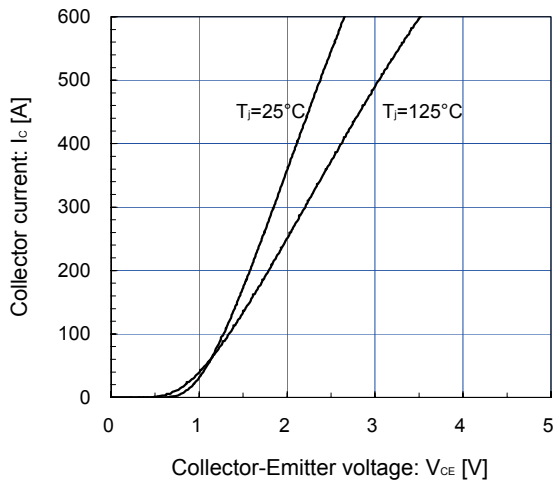
$T_j = 125^\circ\text{C}$ / chip



[T1, T2]

Collector current vs. Collector-Emittor voltage (typ.)

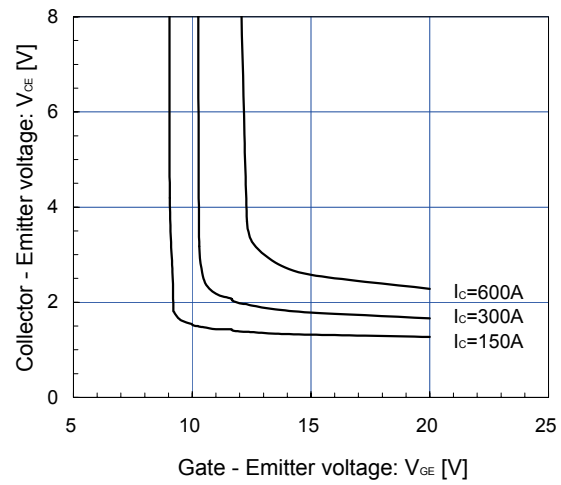
$V_{GE} = 15\text{V}$ / chip



[T1, T2]

Collector-Emittor voltage vs. Gate-Emittor voltage (typ.)

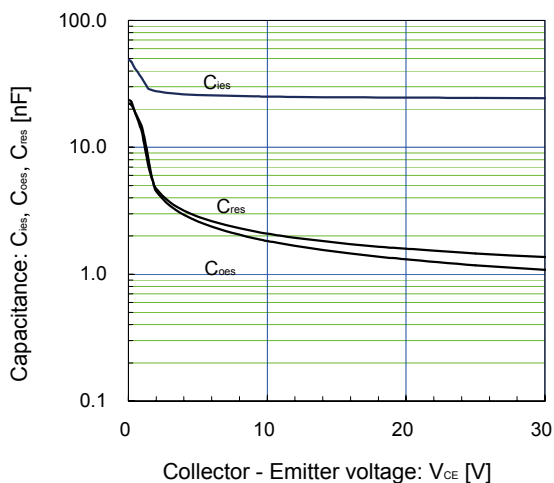
$T_j = 25^\circ\text{C}$ / chip



[T1, T2]

Capacitance vs. Collector-Emittor voltage (typ.)

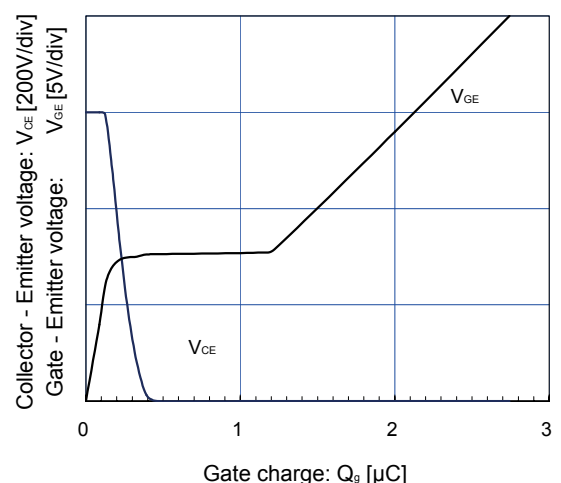
$V_{GE} = 0\text{V}$, $f = 1\text{MHz}$, $T_j = 25^\circ\text{C}$



[T1, T2]

Dynamic gate charge (typ.)

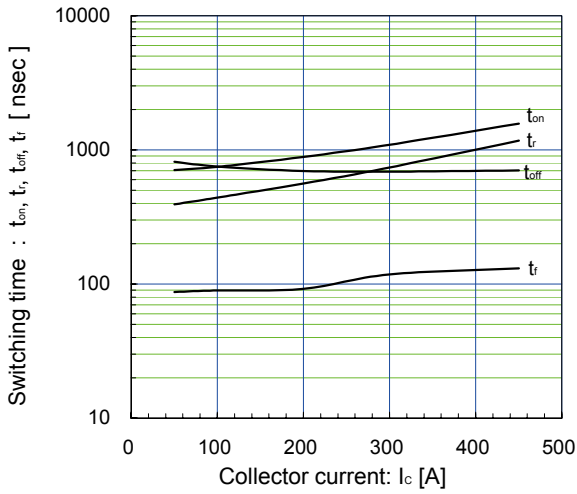
$V_{CC} = 600\text{V}$, $I_c = 300\text{A}$, $T_j = 25^\circ\text{C}$



[SW mode A]

Switching time vs. Collector current (typ.)

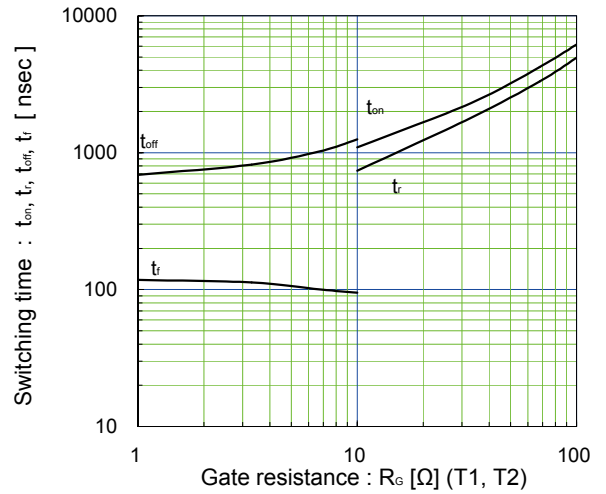
$V_{CC}=800V, V_{GE}=\pm 15V, R_G=+10/-1\Omega, T_J=125^\circ C (T1, T2)$



[SW mode A]

Switching time vs. Collector current (typ.)

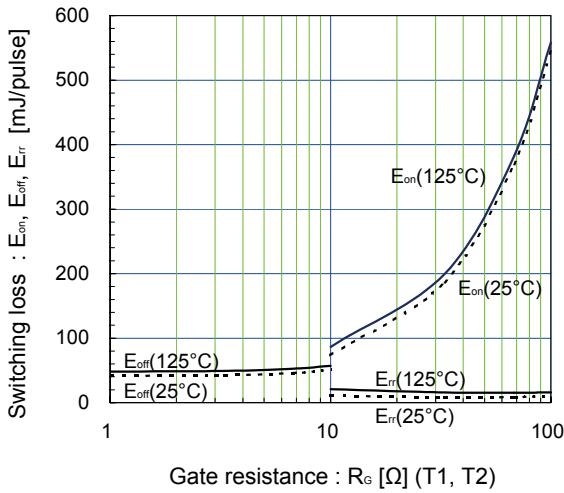
$V_{CC}=800V, I_c=300A, V_{GE}=\pm 15V, T_J=125^\circ C$



[SW mode A]

Switching loss vs. gate resistance (typ.)

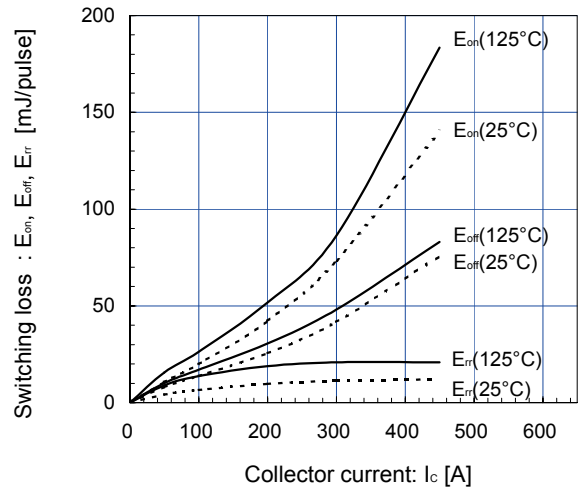
$V_{CC}=800V, I_c=300A, V_{GE}=\pm 15V$



[SW mode A]

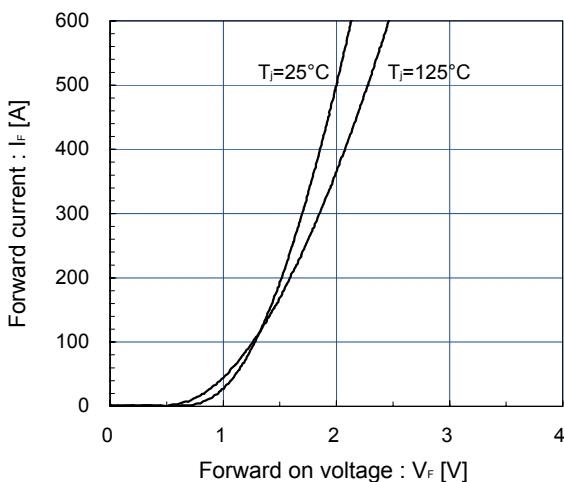
Switching loss vs. Collector current (typ.)

$V_{CC}=800V, V_{GE}=\pm 15V, R_G=+10/-1\Omega (T1, T2)$



[T1, T2]

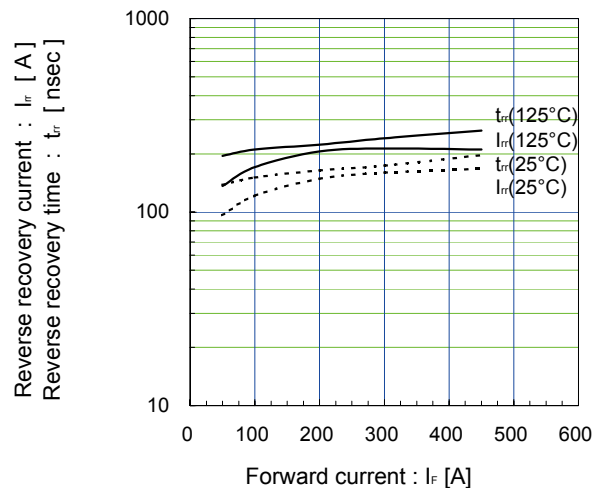
Forward current vs. forward on voltage (typ.)
chip



[T1, T2]

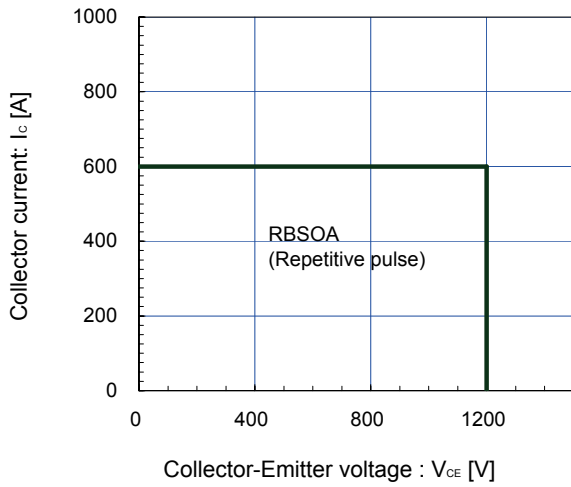
Reverse recovery characteristics (typ.)

$V_{CC}=800V, V_{GE}=\pm 15V, R_G=+10/-1\Omega (T1, T2)$



Reverse bias safe operating area (max.)

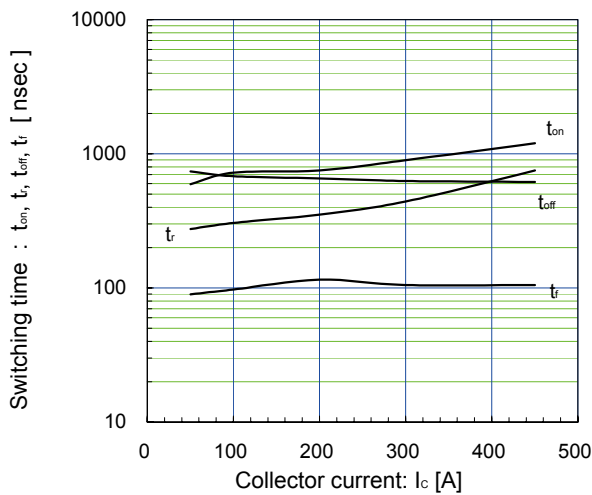
$V_{GE}=15V, -V_{GE} \leq 15V, R_G \geq +10 / -1\Omega, T_j \leq 125^\circ C, L_s = 46nH$ (T1, T2)
T1, T2 (Terminal)



[SW mode C]

Switching time vs. Collector current (typ.)

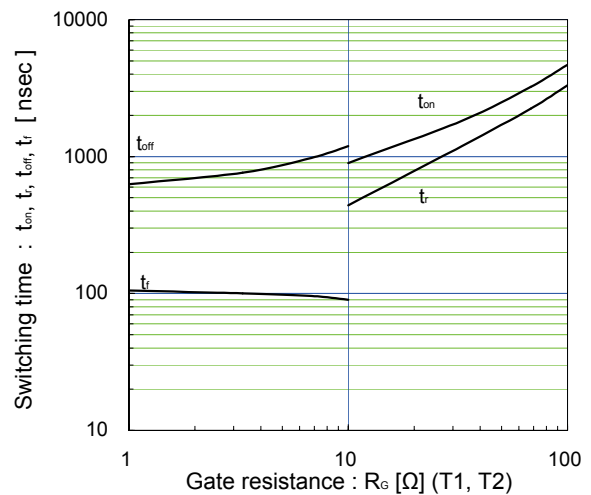
$V_{CC}=400V, V_{GE}=\pm 15V, R_G=+10/-1\Omega, T_j=125^\circ C$ (T1, T2)



[SW mode C]

Switching time vs. Collector current (typ.)

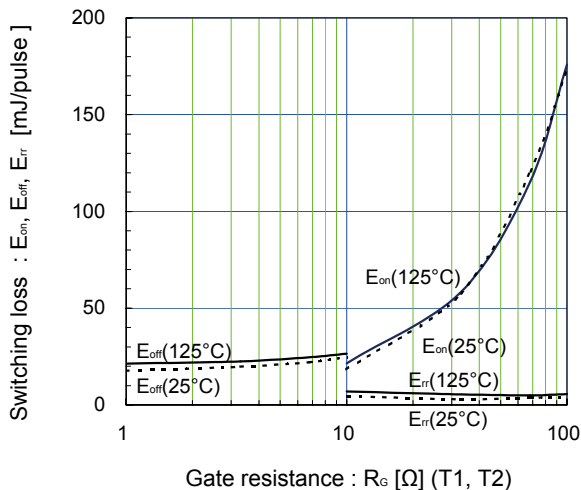
$V_{CC}=400V, I_c=300A, V_{GE}=\pm 15V, T_j=125^\circ C$



[SW mode C]

Switching loss vs. gate resistance (typ.)

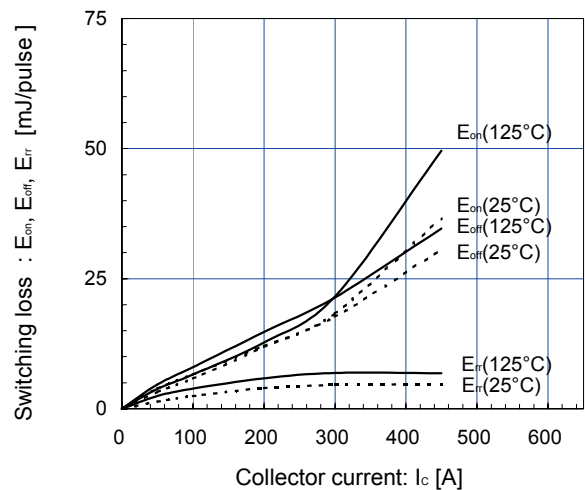
$V_{CC}=400V, I_c=300A, V_{GE}=\pm 15V$

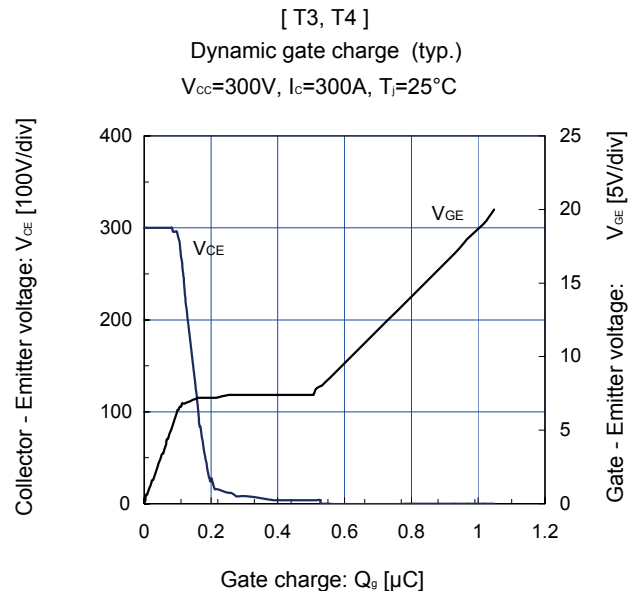
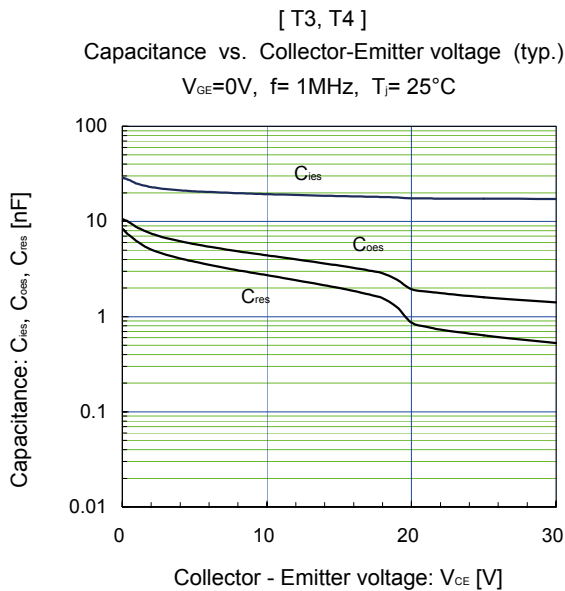
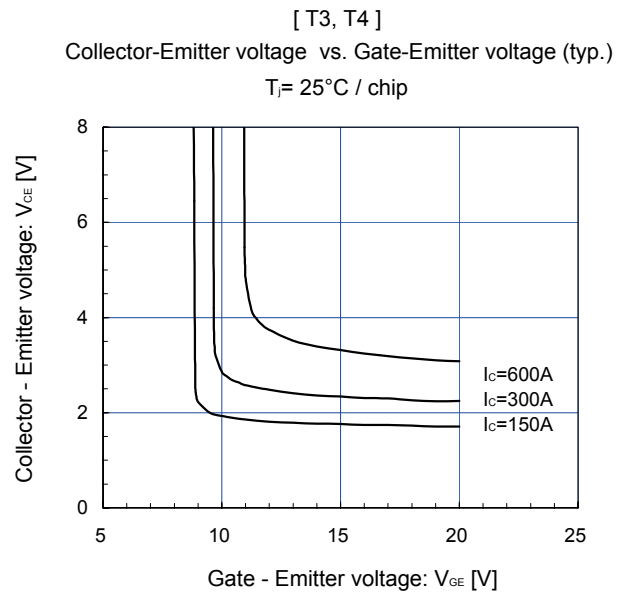
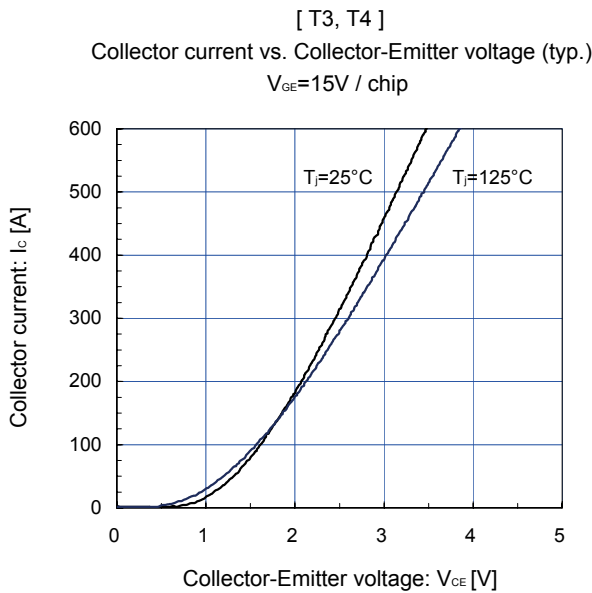
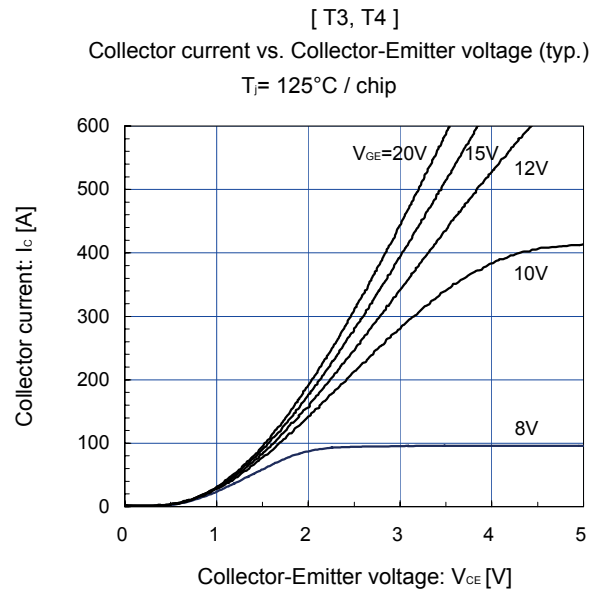
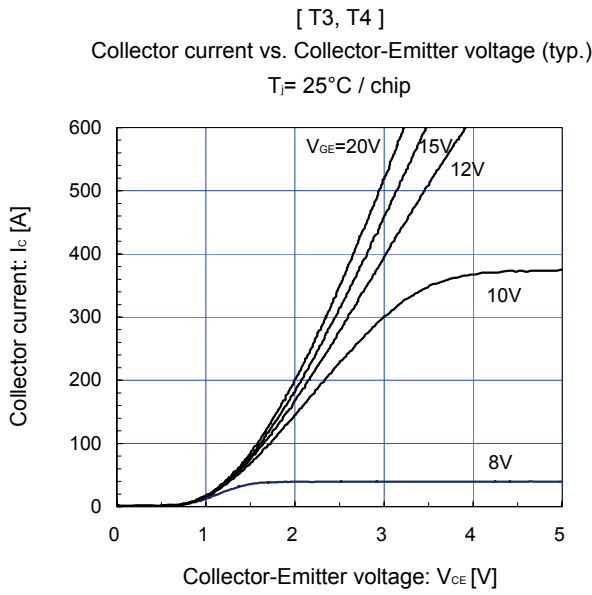


[SW mode C]

Switching loss vs. Collector current (typ.)

$V_{CC}=400V, V_{GE}=\pm 15V, R_G=+10/-1\Omega$ (T1, T2)

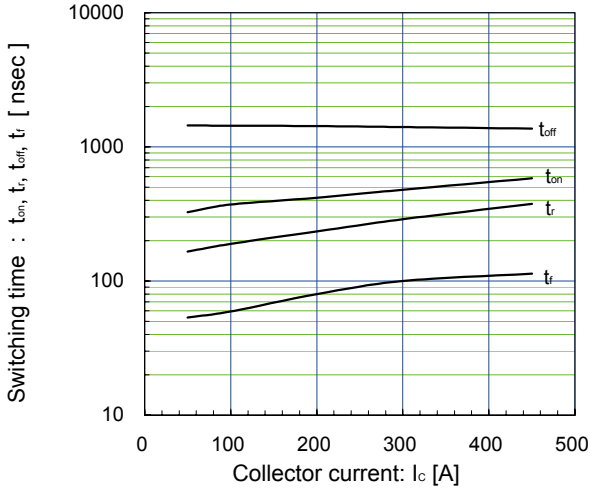




[SW mode B]

Switching time vs. Collector current (typ.)

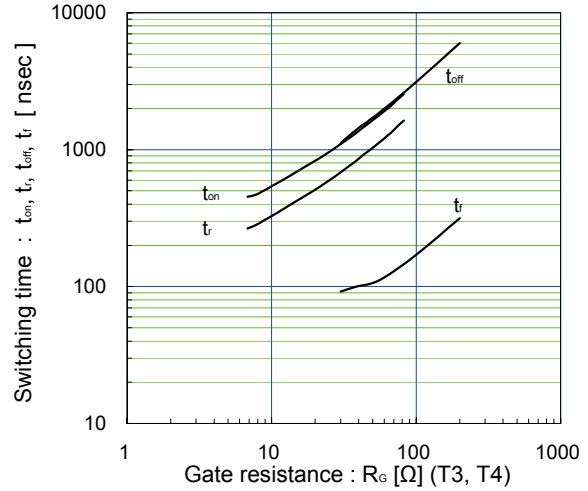
$V_{CC}=400V, V_{GE}=\pm 15V, R_G=+8.2/-39\Omega, T_J=125^\circ C (T_3, T_4)$



[SW mode B]

Switching time vs. Collector current (typ.)

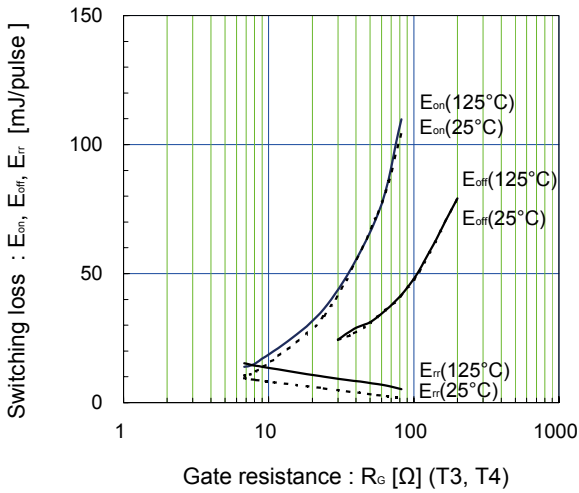
$V_{CC}=400V, I_c=300A, V_{GE}=\pm 15V, T_J=125^\circ C$



[SW mode B]

Switching loss vs. gate resistance (typ.)

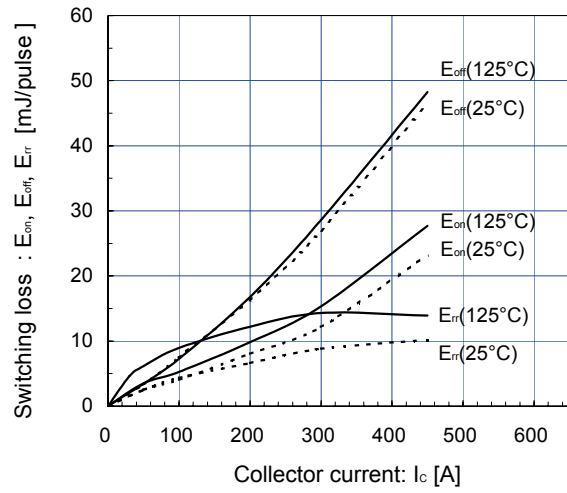
$V_{CC}=400V, I_c=300A, V_{GE}=\pm 15V$



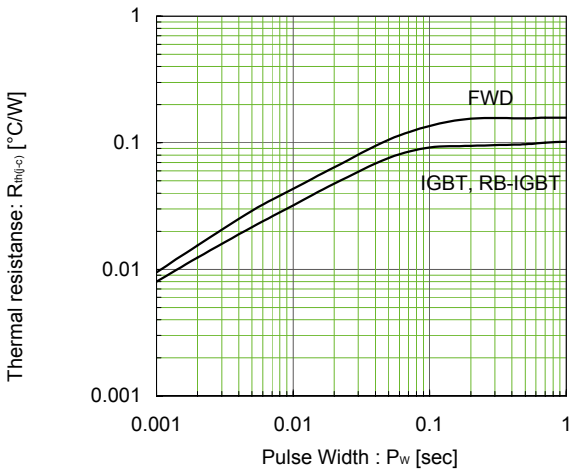
[SW mode B]

Switching loss vs. Collector current (typ.)

$V_{CC}=400V, V_{GE}=\pm 15V, R_G=+8.2/-39\Omega (T_3, T_4)$



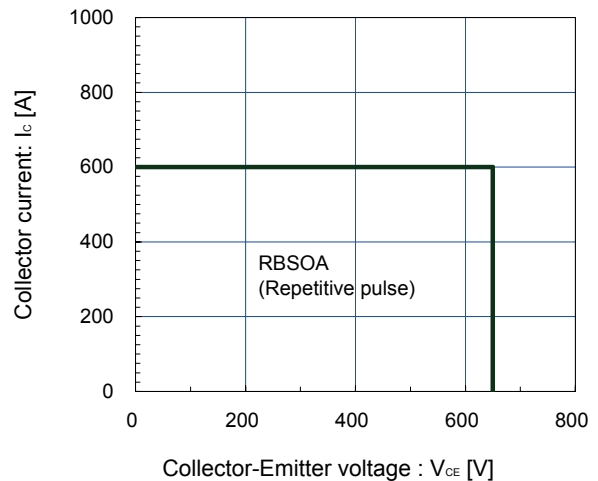
Transient Thermal Resistance (max.)



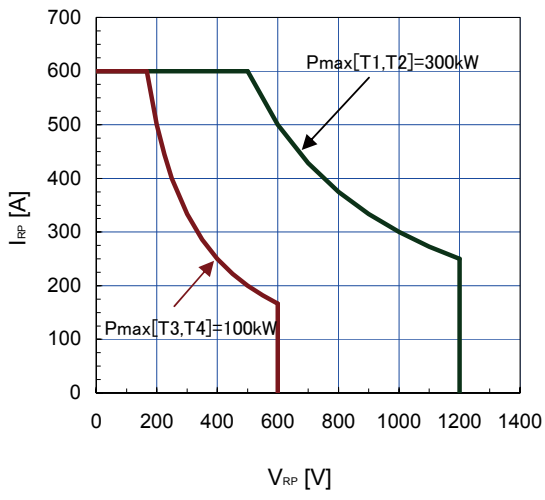
Reverse bias safe operating area (max.)

$V_{GE} = 15V, -V_{GE} \leq 15V, R_G \geq +8.2 / -39\Omega, T_J \leq 125^\circ C, L_S = 46nH (T_3, T_4)$

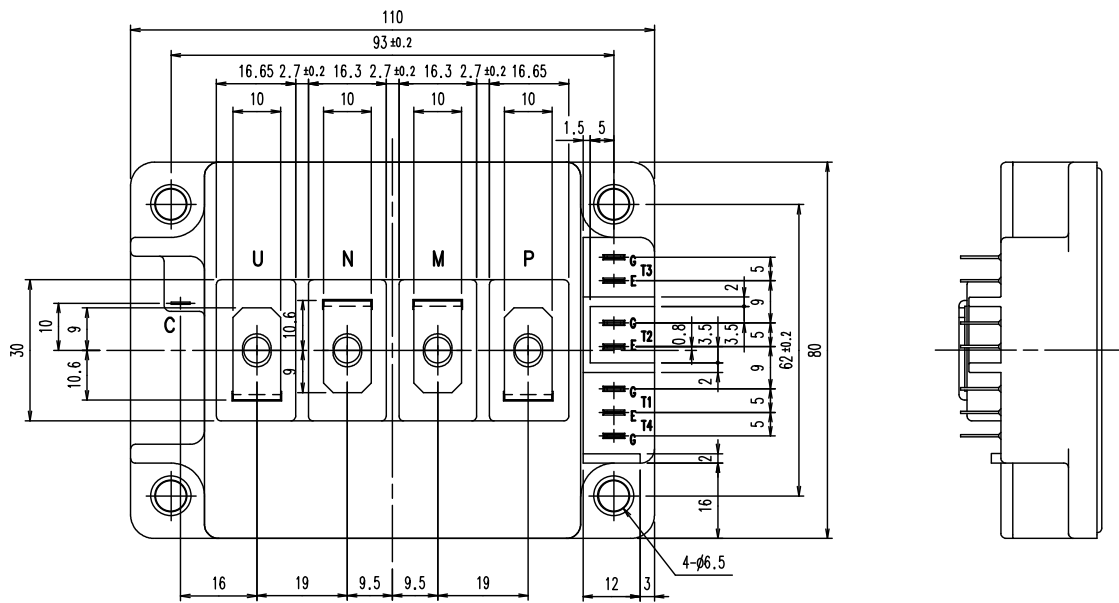
T3, T4 (Terminal)



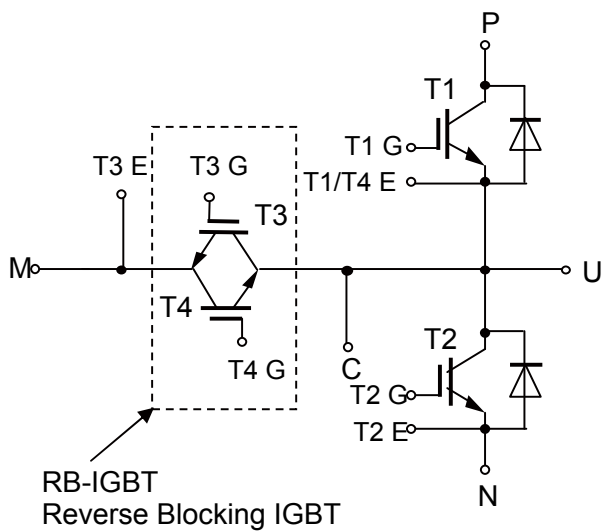
Reverse recovery withstand capability for FWD, RB-IGBT
 $T_j=125^\circ\text{C}$



■ Outline Drawings, mm



■ Equivalent Circuit Schematic



WARNING

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